

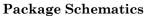
3.5x2.8mm PLCC4 SMD LED

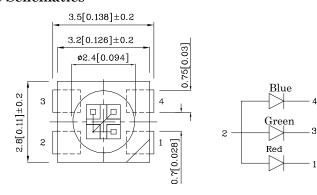
Features

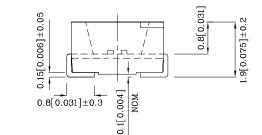
- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant.



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES







Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Red (AlGa InP)	Green (InGa N)	Blue (InGa N)	Unit	Operating Characteristics (T _A =25°C)		Red (AlGaIn P)	Green (InGa N)	Blue (InGa N)	Unit
Reverse Voltage	V_{R}	5	5	5	V	Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2	3.3	3.3	V
Forward Current	$\mathbf{I}_{\mathbf{F}}$	50	30	30	mA	Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	2.5	4.1	4	V
Forward Current (Peak)	0 Duty Cycle i _{FS}	195	150	150	mA	Reverse Current (Max.) (V _R =5V)	I_{R}	10	50	50	μА
1/10 Duty Cycle 0.1ms Pulse Width						Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λР	630*	515*	460*	nm
Power Dissipation	P_{D}	125	123	120	mW						
Operating Temperature	$T_{\rm A}$	-40 ~ +85		°C	Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	621*	525*	465*	nm	
Storage Temperature	Tstg										
Electrostatic Discharge Threshold (HBM)		3000	450	250	v	Spectral Line Full Width At Half-Maximum (Typ.)	$ riangle \lambda$	20	35	25	nm
A Relative Humidity between 40% and 60% is recommended in					(I _F =20mA)						

ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Capacitance (Typ.) $(V_F=0V, f=1MHz)$ Part Emitting

InGaN

С 2545100 \mathbf{pF} Luminous Intensity Wavelength Viewing Emitting CIE127-2007* CIE127-2007* Lens-color Angle Color Material (IF=20mA) nm $2\theta \ 1/2$ λP mcd min. typ. AlGaInP 120* 630* Red 218*400* Green InGaN 497*515*120° Water Clear

 55^{*}

98*

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Blue

Feb 28,2019

Number

XZMEDGCBD45S

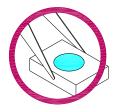
XDSB7192 V5-Z Layout: Maggie L.

460*

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

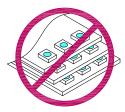
1. Handle the component along the side surfaces by using forceps or appropriate tools.



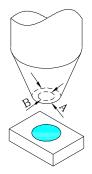
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



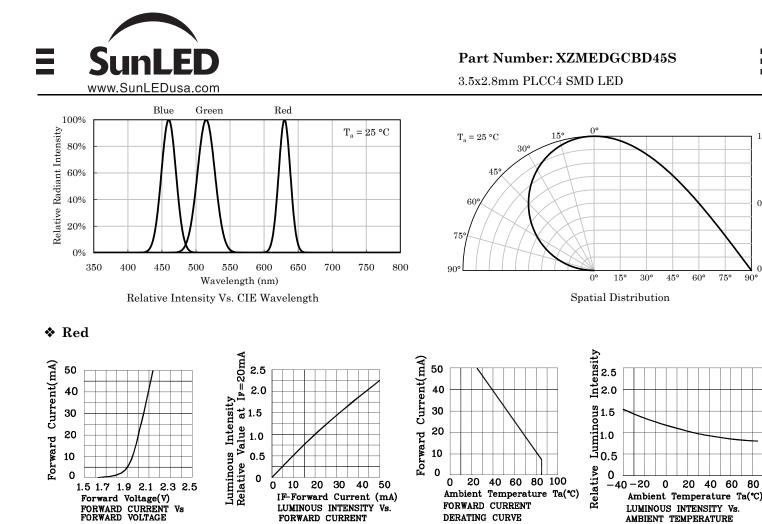
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



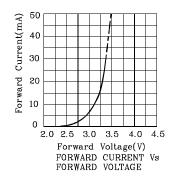
4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

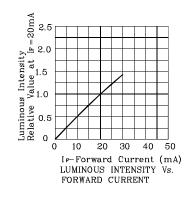


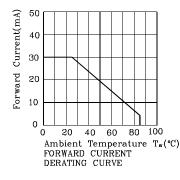
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

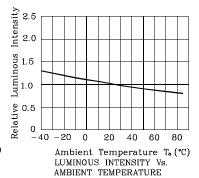




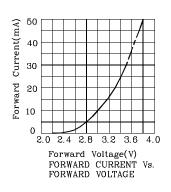




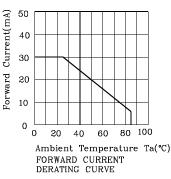


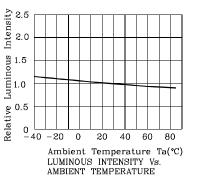


✤ Blue



 $I_F = 20 m A$ 2.52.0 Luminous Intensity Value at 0.1 Relative 0.5 0 10 20 30 40 50 IF-Forward Current (mA) LUMINOUS INTENSITY Vs. FORWARD CURRENT





1.0

0.5

0.0

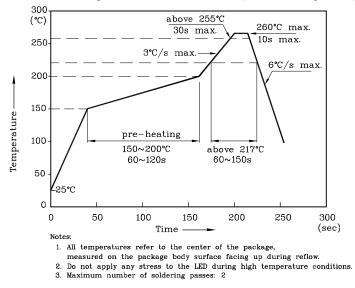
80

75° 90°

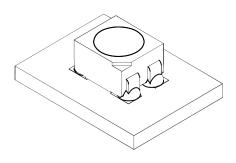


LED is recommended for reflow soldering and soldering profile is shown below.

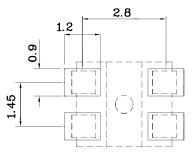
Reflow Soldering Profile for SMD Products (Pb-Free Components)



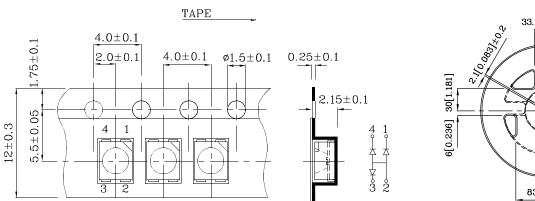
✤ The device has a single mounting surface. The device must be mounted according to the specifications.

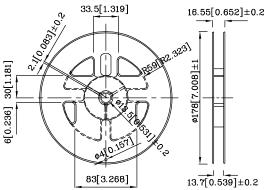


Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension





Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

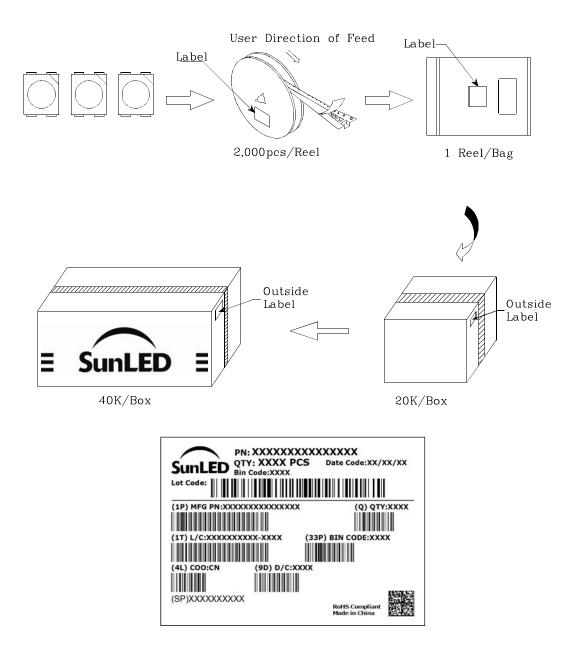
Tape Specification (Units : mm)

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not renant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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